



QSFP/QSFP+

TE Internal #: 1761987-9
QSFP/QSFP+, QSFP, QSFP+ & zQSFP+, Connector, Data Rate (Max) 14 Gb/s, Board-to-Board, 38 Position, .032 in [.8 mm] Centerline, Printed Circuit Board

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Connectors > Pluggable IO Connectors & Cages > QSFP, QSFP+ & zQSFP+



Pluggable I/O Product Type: **Connector**
Data Rate (Max): **14 Gb/s**
Connector System: **Board-to-Board**
Number of Positions: **38**
Centerline (Pitch): **.8 mm [.032 in]**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Form Factor | QSFP+ |
| Pluggable I/O Product Type | Connector |
| Connector System | Board-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|---------------------|----|
| Number of Positions | 38 |
|---------------------|----|

Electrical Characteristics

| | |
|-----------------|---------|
| Data Rate (Max) | 14 Gb/s |
|-----------------|---------|

Contact Features

| | |
|---|----------------|
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Thickness | .76 µm[30 µin] |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Current Rating (Max) | .5 A |

Termination Features

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|---|---------------|
| Termination Method to Printed Circuit Board | Surface Mount |
|---|---------------|

Mechanical Attachment



| | |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

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|--------------------|----------------|
| Centerline (Pitch) | .8 mm[.032 in] |
|--------------------|----------------|

Dimensions

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|-----------------------------|------------------|
| PCB Thickness (Recommended) | 1.45 mm[.057 in] |
|-----------------------------|------------------|

Usage Conditions

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|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
|-----------------------------|----------------------------|

Operation/Application

| | |
|-------------------------------------|------------|
| For Use With Pluggable I/O Products | QSFP+ Cage |
| Circuit Application | Signal |

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

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|------------------|------------|
| Packaging Method | Reel, Tape |
|------------------|------------|

Product Compliance

For compliance documentation, visit the product page on [TE.com](https://www.te.com)>

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUL 2021 (219) Candidate List Declared Against: JUL 2021 (219) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous